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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/511,792	05/09/2005	Jean-Pierre Radenne	003D.0032.U1(US)	6292

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EXAMINER

CHU, CHRIS C

ART UNIT	PAPER NUMBER
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2815

DATE MAILED: 09/25/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary

Application No.

10/511,792

Applicant(s)

RADENNE ET AL.

Examiner

Chris C. Chu

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-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 19 June 2006.
2a) ☐ This action is FINAL. 2b) ☒ This action is non-final.
3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1 - 15 is/are pending in the application.
4a) Of the above claim(s) _____ is/are withdrawn from consideration.
5) ☐ Claim(s) _____ is/are allowed.
6) ☒ Claim(s) 1 - 15 is/are rejected.
7) ☐ Claim(s) _____ is/are objected to.
8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☒ The specification is objected to by the Examiner.
10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
a) ☒ All b) ☐ Some * c) ☐ None of:
1. ☒ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. _____.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- 1) ☒ Notice of References Cited (PTO-892)
2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
3) ☐ Information Disclosure Statement(s) (PTO/SB/08)
Paper No(s)/Mail Date _____.
4) ☐ Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____.
5) ☐ Notice of Informal Patent Application
6) ☐ Other: _____.

DETAILED ACTION

Response to Amendment

1. Applicant's amendment filed on June 19, 2006 has been received and entered in the case.

Election/Restrictions

2. Since the newly amended claims 1 – 4 and the original claims 5 – 15 has same essential features as specified in PCT Rule 13.1 and MPEP §806.03, hence the restriction requirement mailed on February 17, 2006 and the previous Office action are withdrawn.

Specification

3. The abstract of the disclosure is objected to because “Figure 1” shouldn't be under the abstract. Correction is required. See MPEP § 608.01(b).

Since applicant does not amend the abstract or provide a remark, the objection to the disclosure is maintained.

Claim Objections

4. Claims 5 – 15 are objected to because of the following informalities:
 - (A) In claims 5 – 13, “characterised” should be --characterized--.

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(B) In claim 9, “an adhesive” should be --the first adhesive-- because the term “an adhesive” lacks antecedent basis.

(C) In claim 14, after “5” insert --,--.

(D) In claim 15, after “1” insert --,--.

Appropriate correction is required.

Claim Rejections - 35 USC § 102

5. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless --

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

6. Claims 1, 3 – 5, 7 – 11, 14 and 15 are rejected under 35 U.S.C. 102(b) as being anticipated by Hoppe et al. (U. S. Pat. No. 5,637,858).

Regarding claim 1, Hoppe et al. discloses in e.g., Fig. 3 an electronic microcircuit module tape (3; column 3, line 38 and see e.g., Fig. 8) including

- a substrate (11 and 5; column 3, lines 58 and 59),
- at least one contact area (the contact area on the element 5; column 3, line 59) on a first face of this substrate (see e.g., Fig. 3),
- a second face of this substrate (11) capable of accommodating an integrated circuit (17; column 3, lines 60 and 61), wherein the tape (3; see e.g., Fig. 8) further includes (see e.g., Fig. 8 and column 6, line 32),

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- a first adhesive means (22; column 3, line 67) to retain a first face of a mask (25; column 3, line 66) in position against the second face of the substrate (see e.g., Fig. 3), and
- wherein the mask (25) is perforated to form a window (26; see e.g., Fig. 3 and column 4, line 1) around the integrated circuit (17).

Regarding claim 3, Hoppe et al. discloses in e.g., Fig. 3 the mask (25) has a thickness, defined with regard to the second face of the substrate (11) on which it is mounted, greater than the height of the integrated circuit (17; see e.g., Fig. 3).

Regarding claim 4, Hoppe et al. discloses in e.g., Fig. 3 the first adhesive means (22) enables the integrated circuit to be retained on the substrate.

Regarding claim 5, Hoppe et al. discloses in e.g., Fig. 3 and Fig. 8 a method for conditioning an electronic microcircuit module (3), characterized in that it includes the following stages consisting of

- creating a contact area (the contact area on the element 5) on a first face of a substrate tape (11 and 5),
- arranging a first adhesive means (22) between a second face of the substrate (11) and a first face of a mask tape (25), to keep the mask (25) in position against the second face (see e.g., Fig. 3 and Fig. 8),
- perforating (26) the mask tape (11) so that a mask window (26) is facing the contact area (see e.g., Fig. 3 and Fig. 8), and
- arranging a second adhesive means (29; column 4, lines 7 and 8) on the second face of the mask (25; see e.g., Fig. 3).

Regarding claim 7, Hoppe et al. discloses in e.g., Fig. 3 and Fig. 8 characterized in that the mask (25) has the form of a tape including several windows (26) which are laminated on a support including several contact area before separation into individual units (see e.g., Fig. 8).

Regarding claim 8, Hoppe et al. discloses in e.g., Fig. 3 and Fig. 8 characterized in that the stage consisting in retaining the mask (25) in position against the second face of the substrate (11) includes an operation consisting of: laminating the first adhesive (22) means on this second face of the substrate (11; see e.g., Fig. 3).

Regarding claim 9, Hoppe et al. discloses in e.g., Fig. 3 and Fig. 8 characterized in that the stage consisting in arranging an adhesive (22) means on the mask (25) includes an operation consisting of depositing the adhesive means on the mask (column 6, lines 21 – 26), and then perforating this mask (25) before laminating it against the second face of the substrate (11; see e.g., Fig. 8).

Regarding claim 10, Hoppe et al. discloses in e.g., Fig. 3 and Fig. 8 characterized in that it includes a subsequent stage consisting in gluing an integrated circuit (17) to the second face of the substrate, on the first adhesive means (see e.g., Fig. 8).

Regarding claim 11, Hoppe et al. discloses in e.g., Fig. 3 and Fig. 8 characterized in that it includes a stage consisting of: gluing the mask (25) equipped with an electronic circuit to the bottom of a card recess (9; see e.g., Fig. 1 and Fig. 3).

Regarding claim 14, Hoppe et al. discloses in e.g., Fig. 3 and Fig. 8 separating the individual module (3) in the form of a parallelepiped (see e.g., Fig. 1 and Fig. 3).

Regarding claim 15, Hoppe et al. discloses in e.g., Fig. 3 a second adhesive (29) means dispensed on a second face of the mask (25; see e.g., Fig. 3).

Claim Rejections - 35 USC § 103

7. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

8. Claims 2 and 6 are rejected under 35 U.S.C. 103(a) as being unpatentable over Hoppe et al. in view of Atsumi (U. S. Pat. No. 5,736,781).

Regarding claims 2 and 6, while Hoppe et al. discloses the use of the mask (25) and a card (1; column 3, line 41), Hoppe et al. does not disclose the material of the card to be identical to that of the mask's material (i.e., polyvinyl chloride; column 3, lines 1 – 6 of Hoppe et al.). Atsumi teaches in e.g., Fig. 2 a mask (12; column 3, lines 16 and 17) being made from a material (i.e., polyvinyl chloride) identical to that of a card (40; column 3, lines 61 and 62) provided receive a module (1; column 4, line 8). It would have been obvious to one of ordinary skill in the art at the time when the invention was made to apply the polyvinyl chloride of Atsumi as the specific material to form the card of Hoppe et al. as taught by Atsumi to provide similar rigidity as the card body (column 3, lines 16 and 17).

9. Claims 12 and 13 are rejected under 35 U.S.C. 103(a) as being unpatentable over Hoppe et al. in view of Leydier et al. (U. S. Pat. No. 6,217,685).

Regarding claims 12 and 13, while Hoppe et al. discloses the use of the gluing the mask into the recess of the card, Hoppe et al. does not disclose the specific material (claim 12) and process (claim 13) of the glue. Leydier et al. teaches in e.g., Fig. 1 depositing cyanoacrylate glue

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(14; column 3, lines 8 and 9) between a mask (131; column 2, lines 60 and 61) and the bottom of a recess (12; column 2, line 57), and soldering by emission of ultrasound waves (column 3, lines 17 – 21). It would have been obvious to one of ordinary skill in the art at the time when the invention was made to apply the cyanoacrylate glue and the ultrasound waves of Leydier et al. as the specific material and process to glue the mask to the recess of a card of Hoppe et al. as taught by Leydier et al. to increase production capacity by reducing the pressing time (column 3, lines 22 – 29).

Response to Arguments

10. Applicant's arguments with respect to claim 1 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Chris C. Chu whose telephone number is 571-272-1724. The examiner can normally be reached on 11:30 - 8:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kenneth Parker can be reached on 571-272-2298. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

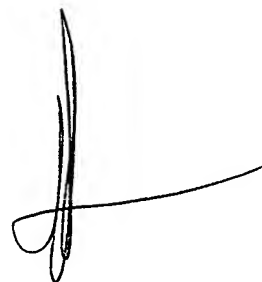
Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR.

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Chris C. Chu
Examiner
Art Unit 2815

c.c.
Sunday, September 17, 2006

A handwritten signature in black ink, appearing to be 'K. Parker', with a long horizontal stroke extending to the right.

KENNETH PARKER
SUPERVISORY PATENT EXAMINER